

## Description

The MK3732-17 is a low cost, low jitter, high performance VCXO and PLL clock synthesizer designed to replace expensive VCXO modules and oscillators. The on-chip Voltage Controlled Crystal Oscillator (VCXO) accepts a 0 to 3.3 V input voltage to cause the output clocks to vary by  $\pm 100$  ppm. Using ICS' patented VCXO and analog Phase-Locked Loop (PLL) techniques, the device uses an inexpensive pullable crystal input to produce one or two output clocks.

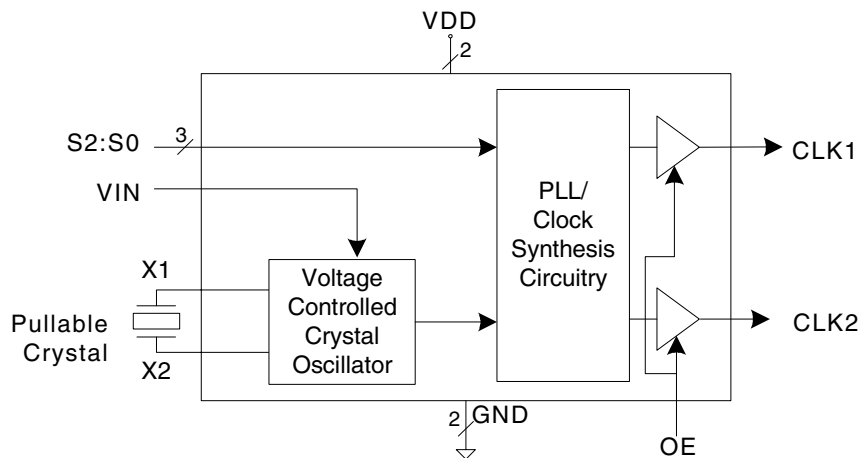
The MK3732-17 is an upgrade to the MK3732-07, and is recommended for new designs.

ICS manufactures the largest variety of xDSL clock synthesizers for all applications. Consult ICS to eliminate VCXOs, crystals, and oscillators from your board.

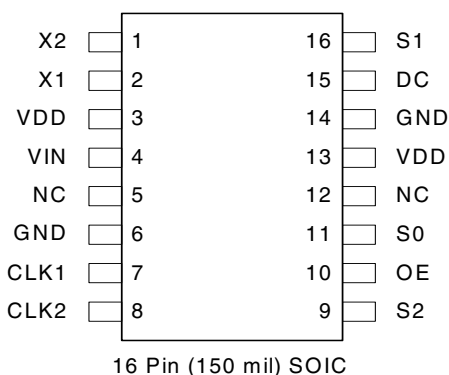
## Features

- Packaged in 16 pin (150 mil) SOIC
- Replaces a VCXO and oscillator
- Ideal for Asymmetrical Digital Subscriber Line (ADSL) chipsets
- Uses an inexpensive pullable crystal
- On-chip patented VCXO with pull range of 200 ppm ( $\pm 100$  ppm) minimum
- VCXO tuning voltage of 0 to 3.3 V
- 12 mA output drive capability at TTL levels
- Advanced, low power, sub-micron CMOS process
- Operating voltage of 3.3V
- Industrial temperature range available

## Block Diagram



## Pin Assignment



## Clock Select Table

S2	S1	S0	Input	CLK1	CLK2
0	0	0	13.248	35.328	29.4
0	0	M	13.248	35.328	47.1
0	0	1	13.248	35.328	40.4
0	1	0	13.248	42.4	35.328
0	1	M	17.664	24.73	35.328
0	1	1	17.664	35.328	OFF
1	0	0	23.552	49.46	35.328
1	0	M	17.664	49.46	35.328
1	0	1	13.248	35.328	Off
1	1	0	13.248	2.208	Off
1	1	M	13.248	24.73	35.328
1	1	1	13.248	49.46	35.328

0=connect directly to GND

M=leave unconnected (floating)

1=connect directly to VDD

## Pin Descriptions

Pin Number	Pin Name	Pin Type	Pin Description
1	X2	Input	Crystal connection. Connect to a pullable crystal. See table above.
2	X1	Input	Crystal connection. Connect to a pullable crystal. See table above.
3	VDD	Power	Connect to +3.3V.
4	VIN	Input	Voltage input to VCXO. Zero to 3.3V signal which controls the VCXO frequency.
5	NC	--	No Connect. Okay to connect to VDD or GND (to match MK3732-07).
6	GND	Power	Connect to ground.
7	CLK1	Output	Clock output #1 per table above.
8	CLK2	Output	Clock output #2 per table above.
9	S2	Input	Select input #2. Selects outputs per table above. Internal pull-up resistor.
10	OE	Input	Output enable. Tri-states outputs when low. Internal pull-up resistor.
11	S0	Input	Select input #0. Selects outputs per table above.
12	NC	--	No Connect. Okay to connect to VDD or GND (to match MK3732-07).
13	VDD	Power	Connect to +3.3V.
14	GND	Power	Connect to ground.
15	DC	-	Don't connect. Do not connect anything to this pin.
16	S1	Input	Select input #1. Selects outputs per table above.

## External Component Selection

The MK3732-17 requires a minimum number of external components for proper operation.

### Decoupling Capacitors

Decoupling capacitors of 0.01 $\mu$ F should be connected between VDD and GND on pins 3 and 6, and on pins 13 and 14, as close to the MK3732-17 as possible. For optimum device performance, the decoupling capacitors should be mounted on the component side of the PCB. Avoid the use of vias in the decoupling circuit.

### Series Termination Resistor

When the PCB traces between the clock outputs and the loads are over 1 inch, series termination should be used. To series terminate a 50 $\Omega$  trace (a commonly used trace impedance) place a 33 $\Omega$  resistor in series with the clock line, as close to the clock output pin as possible. The nominal impedance of the clock output is 20 $\Omega$ .

### Quartz Crystal

The MK3732-17 VCXO function consists of the external crystal and the integrated VCXO oscillator circuit. To assure the best system performance (frequency pull range) and reliability, a crystal device with the recommended parameters must be used, and the layout guidelines discussed in the following section must be followed.

The frequency of oscillation of a quartz crystal is determined by its “cut” and by the load capacitors connected to it. The MK3732-17 incorporates on-chip variable load capacitors that “pull” (change) the frequency of the crystal. The crystal specified for use with the MK3732-17 is designed to have zero frequency error when the total of on-chip + stray capacitance is 14pF.

The external crystal must be connected as close to the chip as possible and should be on the same side of the PCB as the MK3732-17. There should be no vias between the crystal pins and the X1 and X2 device pins. There should be no signal traces underneath or close to the crystal.

Please see application note MAN05 for recommended crystal parameters and suppliers.

### Crystal Tuning Load Capacitors

The crystal traces should include pads for small fixed

capacitors, one between X1 and ground, and another between X2 and ground. Stuffing of these capacitors on the PCB is optional. The need for these capacitors is determined at system prototype evaluation, and is influenced by the particular crystal used (manufacture and frequency) and by PCB layout. The typical required capacitor value is 1 to 4 pF.

To determine the need for and value of the crystal adjustment capacitors, you will need a PC board of your final layout, a frequency counter capable of about 1 ppm resolution and accuracy, two power supplies, and some samples of the crystals which you plan to use in production, along with measured initial accuracy for each crystal at the specified crystal load capacitance, CL.

To determine the value of the crystal capacitors:

1. Connect VDD of the MK3732-17 to 3.3V. Connect pin 4 of the MK3732-17 to the second power supply. Adjust the voltage on pin 4 to 0V. Measure and record the frequency of the CLK output.
2. Adjust the voltage on pin 4 to 3.3V. Measure and record the frequency of the same output.

To calculate the centering error:

$$\text{Error} = 10^6 \times \left[ \frac{(f_{3.3V} - f_{\text{target}}) + (f_{0V} - f_{\text{target}})}{f_{\text{target}}} \right] - \text{error}_{\text{xtal}}$$

Where:

$f_{\text{target}}$  = nominal crystal frequency

$\text{error}_{\text{xtal}}$  = actual initial accuracy (in ppm) of the crystal being measured

If the centering error is less than  $\pm 25$  ppm, no adjustment is needed. If the centering error is more than 25ppm negative, the PC board has excessive stray capacitance and a new PCB layout should be considered to reduce stray capacitance. (Alternately, the crystal may be re-specified to a higher load capacitance. Contact ICS for details.) If the centering error is more than 25ppm positive, add identical fixed centering capacitors from each crystal pin to ground. The value for each of these caps (in pF) is given by:

Trim sensitivity is a parameter which can be supplied by your crystal vendor. If you do not know the value, assume it is 30 ppm/pF. After any changes, repeat the measurement to verify that the remaining error is acceptably low (typically less than  $\pm 25$ ppm).

External Capacitor =

$$2 \times (\text{centering error}) / (\text{trim sensitivity})$$

## Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the MK3732-17. These ratings, which are standard values for ICS commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	7V
All Inputs and Outputs	-0.5V to VDD+0.5V
Ambient Operating Temperature	-40 to +85°C
Storage Temperature	-65 to +150°C
Soldering Temperature	260°C

## Recommended Operation Conditions

Parameter	Min.	Typ.	Max.	Units
Ambient Operating Temperature (MK3732-17SI)	-40		+85	°C
Ambient Operating Temperature (MK3732-17S)	0		+70	°C
Power Supply Voltage (measured in respect to GND)	+3.15		+3.45	V
Reference crystal parameters	Refer to MAN05			

## DC Electrical Characteristics

VDD=3.3V  $\pm 5\%$ , Ambient temperature 0 to +70°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Operating Voltage	VDD		3.15	3.3	3.45	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -12 mA	2.4			V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 12 mA			0.4	V
Output High Voltage (CMOS Level)	V <sub>OH</sub>	I <sub>OH</sub> = -8 mA	VDD-0.4			V
Short Circuit Current	I <sub>OS</sub>			$\pm 50$		mA
Input High Voltage, binary inputs	V <sub>IH</sub>	S2, S1, OE	2.0			V
Input High Voltage, trinary input	V <sub>IH</sub>	S0	VDD-0.5			V

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Input Low Voltage, binary inputs	V <sub>IL</sub>	S2, S1, OE			0.8	V
Input Low Voltage, trinary input	V <sub>IL</sub>	S0			0.5	V
Operating Supply Current	I <sub>DD</sub>	No load		15		mA
Input Capacitance	C <sub>IN</sub>	S2:S0, OE		5		pF
VIN, VCXO Control Voltage	V <sub>IA</sub>		0		3.3	V
Internal Pull-up Resistor	R <sub>PU</sub>	S2:S0, OE		430		kΩ

## AC Electrical Characteristics

VDD = 3.3V ±5%, Ambient Temperature 0 to +70° C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Input Crystal Frequency				13.248		MHz
Output Clock Frequency			See Table on Page 2			MHz
Output Clock Rise Time	t <sub>OR</sub>	0.8 to 2.0V, Note 1			1.5	ns
Output Clock Fall Time	t <sub>OF</sub>	2.0 to 0.8V, Note 1			1.5	ns
Output Clock Duty Cycle	t <sub>D</sub>	At VDD/2, Note 1	40		60	%
Maximum Absolute Jitter	t <sub>j</sub>	Note 1, deviation from mean		±150		ps
Phase Noise, relative to carrier		10 kHz offset		-124		dBc/Hz
Frequency Synthesis Error		Both clocks			0	ppm
VCXO Pullability	F <sub>P</sub>	0V ≤ VIN ≤ 3.3V, Note 2	±100			ppm
VCXO Gain		VIN = (VDD/2)±1, Note 2		150		ppm/V

Note 1: Measured with a 15 pF load.

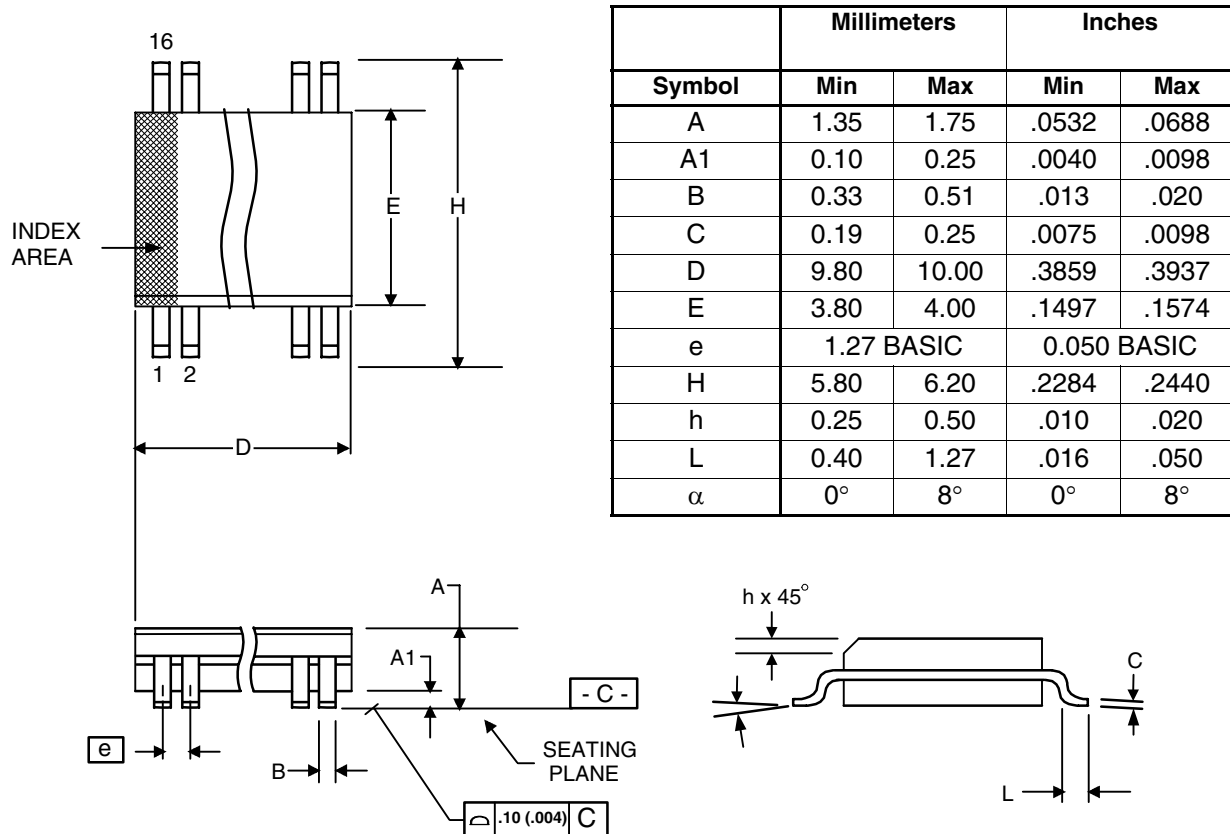
Note 2: External pullable crystal must conform with those listed in application note MAN05

## Thermal Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Thermal Resistance Junction to Ambient	θ <sub>JA</sub>	Still air		120		°C/W
	θ <sub>JA</sub>	1 m/s air flow		115		°C/W
	θ <sub>JA</sub>	3 m/s air flow		105		°C/W
Thermal Resistance Junction to Case	θ <sub>JC</sub>			58		°C/W

## Package Outline and Package Dimensions (16 pin SOIC, 150 Mil. Narrow Body)

Package dimensions are kept current with JEDEC Publication No. 95



## Ordering Information

Part / Order Number	Marking	Shipping packaging	Package	Temperature
MK3732-17S	MK3732-17S	Tubes	16 pin SOIC	0 to +70° C
MK3732-17STR	MK3732-17S	Tape and Reel	16 pin SOIC	0 to +70° C
MK3732-17SI	MK3732-17SI	Tubes	16 pin SOIC	-40 to +85° C
MK3732-17SITR	MK3732-17SI	Tape and Reel	16 pin SOIC	-40 to +85° C

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